MITSUI KINZOKU

型号：FSP-501

- FSP-501是在MicroThin™的超薄铜箔面做树脂涂层的材料，适用于SAP（半加成法）工艺。
  FSP-501 is SAP(Semi Additive Process) material which primer resin
  is caoted on the thin foil surface of MicroThin™.
- 适用于线宽/线距(L/S)=20/20或以下的应用。
  Usable for L/S=20/20 or less fine patterning.

用途/Application

・半导体封装基板
/Semiconductor Package

构成/Composition

生产地点/Production Site

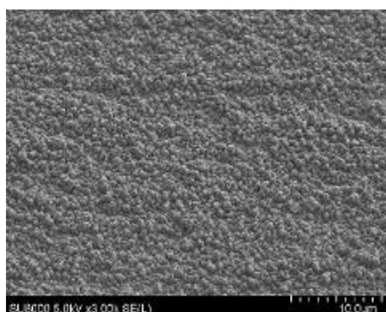
・日本 / Japan

代表性特性数据/Representive data

Model No.	μm	Area weight (w/o Primer) (g/m2)	Laminate side Rz(μm)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)@FR-4
FSP-501	1.5	18	1.4	−	−	−
	2	21	1.4	−	−	−
	3	30	1.4	−	−	−

※上述列表为代表性数据，非保证数据。
This is representative data, not guaranteed.
※Peel Strength为增镀到35μm厚度之后的测试值。
Evaluated after plated up to 35μm。

未覆底层树脂涂层的处理面/
Laminate side before Primer coat



阻剂面/Resist side